

ABSTRACT

PHOTOSENSITIVE RESIN COMPOSITION

This invention provides a photosensitive resin composition and in particular, it provides a photosensitive resin composition comprising a) an acryl-based copolymer obtained by copolymerizing i) a phenylmaleimide-based compound, ii) an unsaturated carbonic acid, unsaturated carbonic anhydride or mixture thereof, and iii) an epoxy group containing unsaturated compound; b) a 1,2-quinonediazide compound; and c) a solvent.

The photosensitive resin composition according to the invention has excellent performances in transmission, insulation, flatness, chemistry resistance and so on, and further, it secures reliable post-process by minimizing outgassing that may occur in interlayer dielectrics by virtue of high heat resistance property so that it is suitable for use in interlayer dielectrics during LCD manufacturing process.